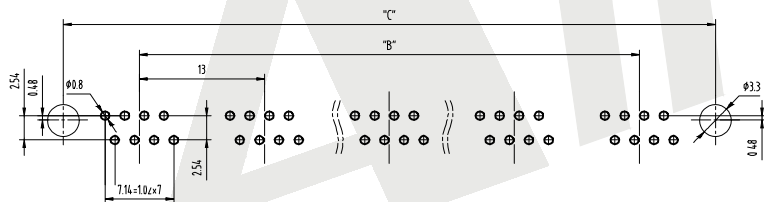
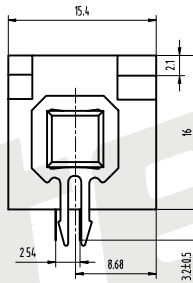
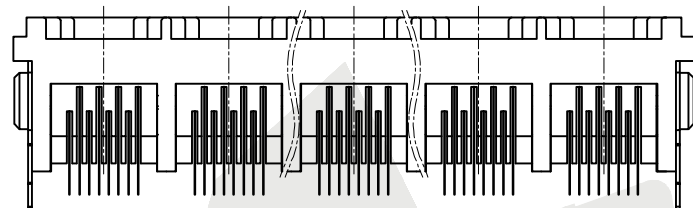
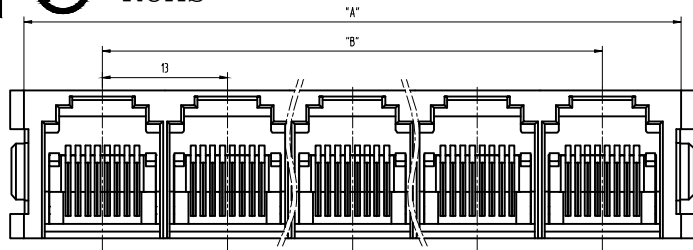


HSF

RoHS



PC Board Layout
Component Side Shown

DIMENSION:

N	"A" ±0.25	"B" ±0.15	"C" ±0.15
1	16.34	0	16.84
2	29.34	13	29.84
3	42.34	26	41.84
4	55.34	39	54.84
6	81.34	65	80.84
8	107.34	91	106.84

NOTES:

MATERIAL:

- 1. HOUSING MATERIAL :GLASS FILLED POYESTER UL94V-0.
- 2. CONTACT MATERIAL :PHOSPHOR BRONZE t=0.3mm
- 3. PLATING :SELECTING GOLD PLATING 1 μ ~50 μ "OVER NICKEL IN CONTACT AREA. 150 μ " TIN PLATIN. OVER NICKEL IN SOLDER AREA
- 4. SHIELD :0.2mmTHICKNESS COPPER WITH NICKEL PLATEI

ELECTRICAL

- 1. VOLTAGE RATING :125VAC RMS
- 2. CURRENT RATING :1.5AMP
- 3. CONTACT RESISTANCE:30MILLIOHMS MAX
- 4. INSULATION RESISTANCE 500MEG OHMS MIN @500V DC
- 5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

MECHANICAL

- 1. DURRABILITY :750 CYCLES MIN
- 2. PCB RETENTTON PRB-SOLDER :1 LB MIN

REVRONMENTAL

- 1. STORAGE : -40° C TO 85° C
- 2. OPERATION :0° C TO 70° C

Order code:

ATRJ5224 - 8P - 8C - X - A - D

① ② ③ ④ ⑤ ⑥

- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact Plating
G0:G0ld flash
G1: 3U" Gold
G2: 5U" Gold
G3:10U" Gold
G4:15U" Gold
G5:30U" Gold
SN:Tin
- ⑤ Shield
A:W/O Shield
B:Half Shield
C:Shield W/Eml
D:Shield W/O Eml
- ⑥ Ports
A:1X1P
B:1X2P
C:1X4P
D:1X5P
E:1X6P
F:1X8P

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
DRAW Wu Feng Rong DATE 23/08/2019
CHECK BobYang DATE 23/08/2019

Antenk® ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE: RJ11 Top entry 8P8C 1X5P,
Full plastic with metal legs

DRAWING NO: ATRJ5224-8P8C-X-A-D

PRODUCT NO: ATRJ5224-8P8C-X-A-D



REV	DESCRIPTION	DATE